



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **KIRA, et al.**

Group Art Unit: **2652**

Serial No.: **09/548,313**

Examiner: **Craig A. Renner**

Filed: **April 12, 2000**

P.T.O. Confirmation No.: **6169**

For: **HEAD ASSEMBLY HAVING INTEGRATED CIRCUIT CHIP COVERED BY LAYER WHICH PREVENTS FOREIGN PARTICLE GENERATION**

RECEIVED

RESPONSE UNDER 37 CFR §1.116

JUN 03 2003

MAILSTOP AF

Technology Center 2600

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

May 29, 2003

*Do not
forget
to file
by 5/29/03*

Sir:

In response to the Office Action dated **January 29, 2003**, extended to **May 29, 2003** by a one month Petition for Extension of Time, please amend the above-identified application as follows:

IN THE CLAIMS:

Amend the claims to read as follows:

1. (Twice Amended) A head assembly comprising:

a mounting surface;

an integrated circuit chip which is mounted on the mounting surface and processes signals;

and

a head slider which is provided with a head and is mounted on the mounting surface,

said integrated circuit chip being covered by a layer,

a height of the integrated circuit chip, including the layer, being lower than a height of the